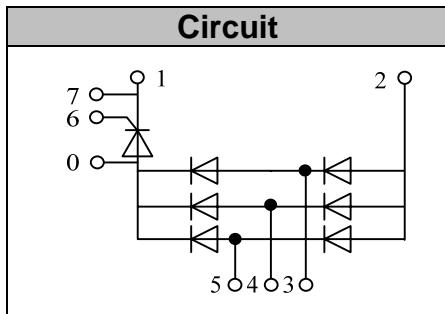




## Three Phase Bridge + Thyristor

**V<sub>RRM</sub> / V<sub>DRM</sub>** 800 to 1600V  
**I<sub>FAV</sub> / I<sub>TAV</sub>** 100Amp



### Features

- Blocking voltage: 800 to 1600V
- Three Phase Bridge and a Thyristor
- Isolated Module package

### Applications

- Inverter for AC or DC motor control
- Current stabilized power supply
- Switching power supply
- UL E243882 approved

### Module Type

TYPE	V <sub>RRM</sub> / V <sub>DRM</sub>	V <sub>RSM</sub>
MSDT100-08	800V	900V
MSDT100-12	1200V	1300V
MSDT100-16	1600V	1700V

### ◆ Diode

### Maximum Ratings

Symbol	Item	Conditions	Values	Units
I <sub>D</sub>	Output Current(D.C.)	T <sub>c</sub> =100°C Three phase full wave	100	A
I <sub>FSM</sub>	Surge forward current	t=10mS T <sub>vj</sub> =45°C	1200	A
i <sup>2</sup> t	Circuit Fusing Consideration		7200	A <sup>2</sup> s
V <sub>isol</sub>	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1min	3000	V
T <sub>vj</sub>	Operating Junction Temperature		-40 to +150	°C
T <sub>stg</sub>	Storage Temperature		-40 to +125	°C
M <sub>t</sub>	Mounting Torque	To terminals(M5)	3±15%	Nm
M <sub>s</sub>		To heatsink(M5)	3±15%	Nm
Weight		Module (Approximately)	210	g

### Thermal Characteristics

Symbol	Item	Conditions	Values	Units
R <sub>th(j-c)</sub>	Thermal Impedance, max.	Junction to Case(TOTAL)	0.18	°C/W
R <sub>th(c-s)</sub>	Thermal Impedance, max.	Case to Heatsink	0.10	°C/W

### Electrical Characteristics

Symbol	Item	Conditions	Values	Units
V <sub>F</sub> M	Forward Voltage Drop, max.	T=25°C I <sub>F</sub> =100A	1.35	V
I <sub>RRM</sub>	Repetitive Peak Reverse Current, max.	T <sub>vj</sub> =25°C V <sub>RD</sub> =V <sub>RRM</sub> T <sub>vj</sub> =150°C V <sub>RD</sub> =V <sub>RRM</sub>	≤0.5 ≤6	mA mA

## ◆Thyristor

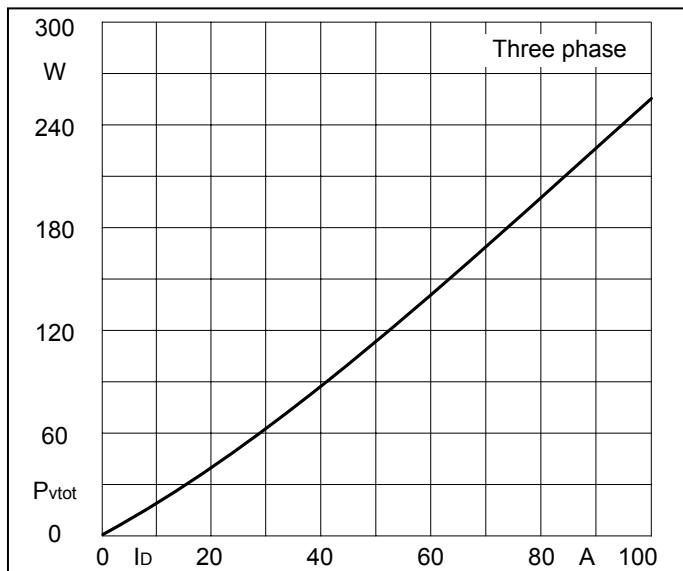
**Maximum Ratings**

Symbol	Item	Conditions	Values	Units
I <sub>TAV</sub>	Average On-State Current	T <sub>C</sub> =92°C, Single Phase half wave 180° conduction	100	A
I <sub>TSM</sub>	Surge On-State Current	T <sub>VJ</sub> =45°C t=10ms (50Hz), sine VR=0	1200	A
i <sup>2</sup> t	Circuit Fusing Consideration		7200	A <sup>2</sup> s
Visol	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1 min	3000	V
T <sub>VJ</sub>	Operating Junction Temperature		-40 to +125	°C
T <sub>STG</sub>	Storage Temperature		-40 to +125	°C
M <sub>T</sub>	Mounting Torque	To terminals(M5)	3±15%	Nm
M <sub>S</sub>		To heatsink(M5)	3±15%	Nm
di/dt	Critical Rate of Rise of On-State Current	T <sub>VJ</sub> =T <sub>VJM</sub> , V <sub>D</sub> =1/2V <sub>DRM</sub> , I <sub>G</sub> =100mA d <sub>iG</sub> /dt=0.1A/μs	150	A/μs
dv/dt	Critical Rate of Rise of Off-State Voltage, min.	T <sub>J</sub> =T <sub>VJM</sub> , V <sub>D</sub> =2/3V <sub>DRM</sub> , linear voltage rise	500	V/μs

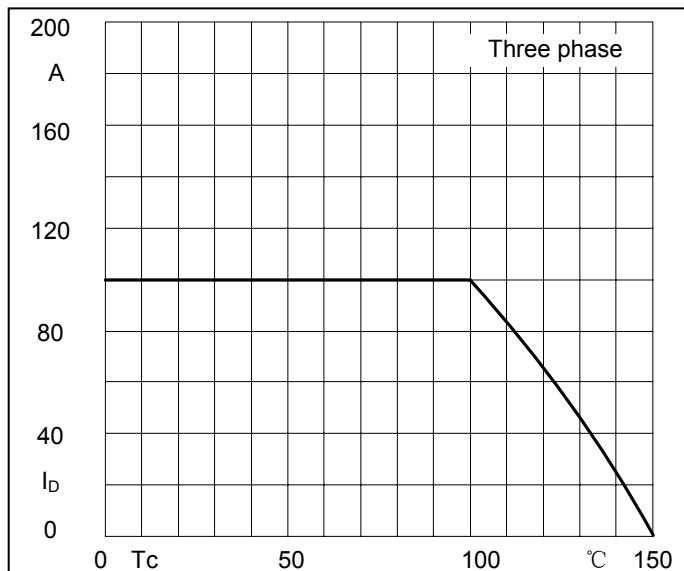
**Electrical and Thermal Characteristics**

Symbol	Item	Conditions	Values			Units
			Min.	Typ.	Max.	
V <sub>TM</sub>	Peak On-State Voltage, max.	T=25°C I <sub>T</sub> =300A			1.70	V
I <sub>RRM</sub> /I <sub>DRM</sub>	Repetitive Peak Reverse Current, max. / Repetitive Peak Off-State Current, max.	T <sub>VJ</sub> =T <sub>VJM</sub> , V <sub>R</sub> =V <sub>RRM</sub> , V <sub>D</sub> =V <sub>DRM</sub>			20	mA
V <sub>TO</sub>	Threshold voltage	T <sub>VJ</sub> = T <sub>VJM</sub>			0.9	V
r <sub>T</sub>	Slope resistance				2	mΩ
V <sub>GT</sub>	Gate Trigger Voltage, max.	T <sub>VJ</sub> = 25°C , V <sub>D</sub> = 6V			3	V
I <sub>GT</sub>	Gate Trigger Current, max.	T <sub>VJ</sub> = 25°C , V <sub>D</sub> = 6V			150	mA
V <sub>GD</sub>	Max. required DC gate voltage	T <sub>VJ</sub> = 125°C , V <sub>D</sub> = 2/3V <sub>DRM</sub>			0.25	V
I <sub>GD</sub>	Max. required DC gate current	T <sub>VJ</sub> = 125°C , V <sub>D</sub> = 2/3V <sub>DRM</sub>			6	mA
I <sub>L</sub>	Maximum latching current	T <sub>VJ</sub> = 25°C , R <sub>G</sub> =33Ω		300	600	mA
I <sub>H</sub>	Maximum holding current	T <sub>VJ</sub> = 25°C , V <sub>D</sub> = 6V		150	250	mA
t <sub>gd</sub>	Gate controlled delay time	T <sub>VJ</sub> = 25°C, I <sub>G</sub> =1A, di <sub>G</sub> /dt=1A/us		1		us
t <sub>q</sub>	Circuit commutated turn-off time	T <sub>VJ</sub> = T <sub>VJM</sub>		100		us
R <sub>th(j-c)</sub>	Thermal Impedance, max.	Junction to Case			0.26	°C/W
R <sub>th(c-s)</sub>	Thermal Impedance, max.	Case to Heatsink			0.10	°C/W

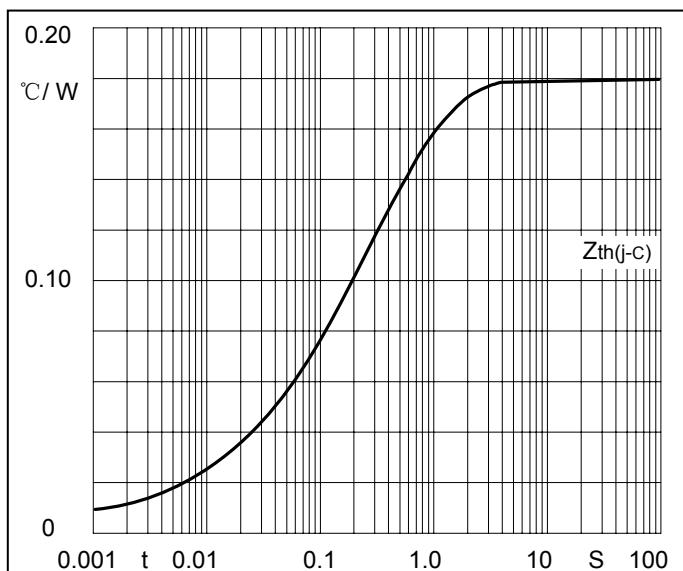
## Performance Curves



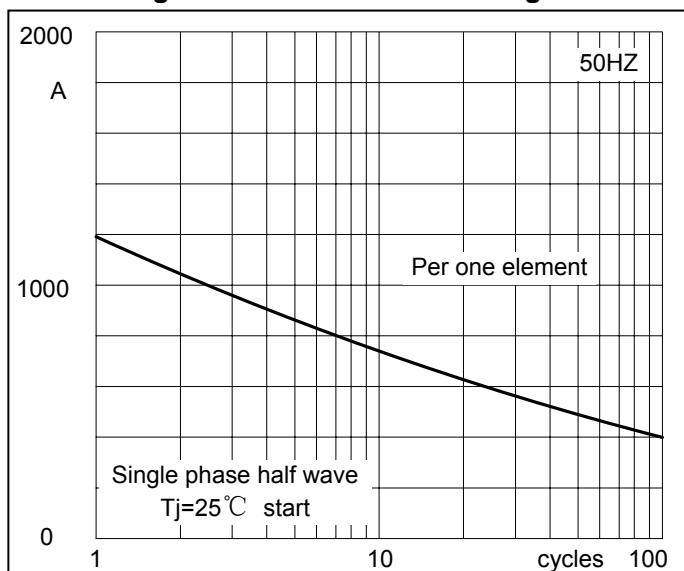
**Fig1. Power dissipation**



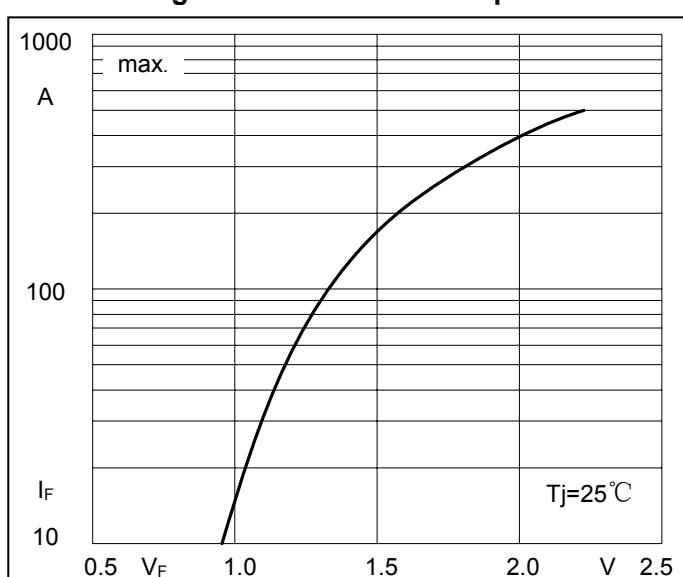
**Fig2. Forward Current Derating Curve**



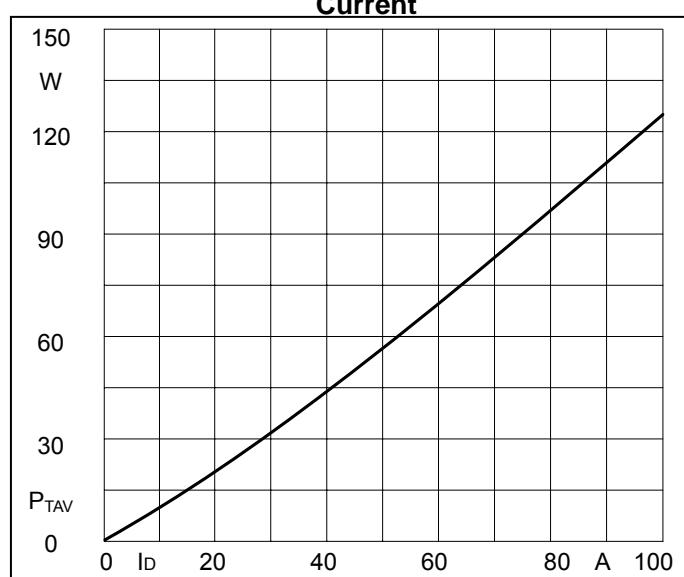
**Fig3. Transient thermal impedance**



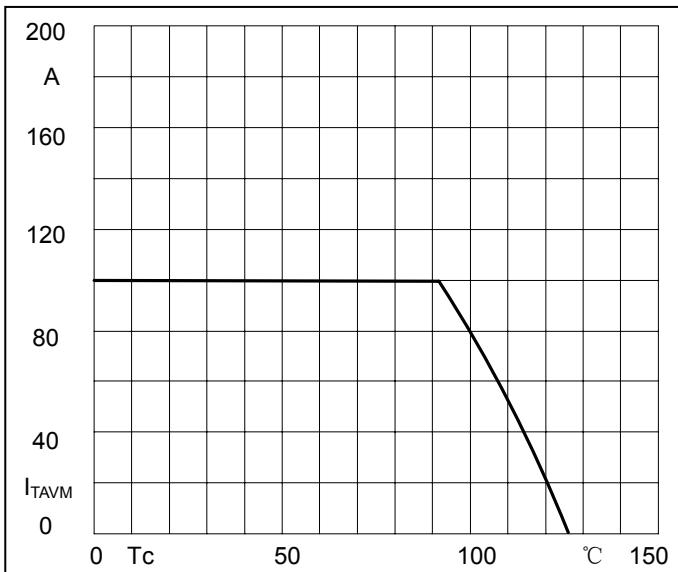
**Fig4. Max Non-Repetitive Forward Surge Current**



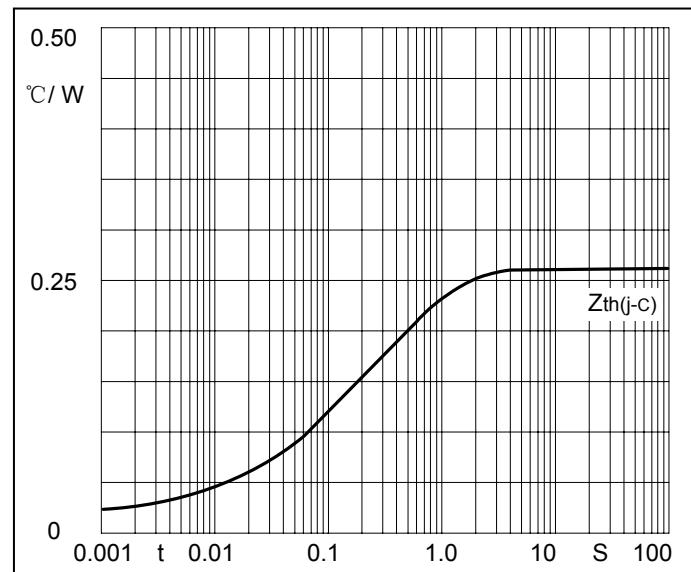
**Fig5. Forward Characteristics**



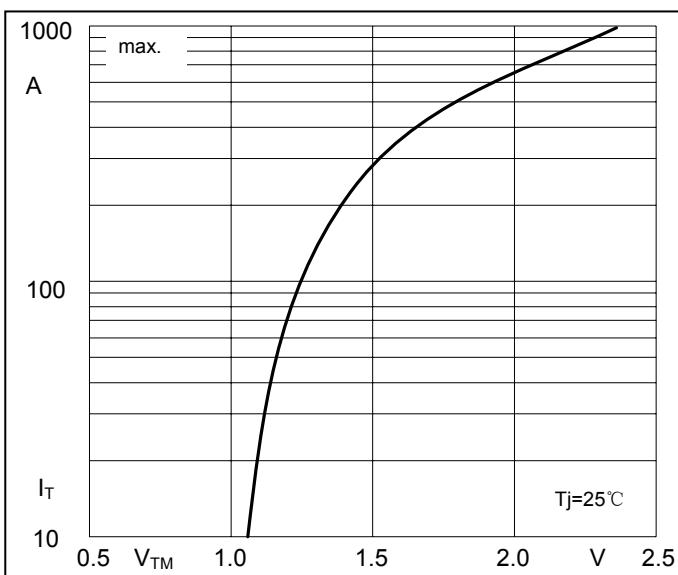
**Fig6. SCR Power dissipation**



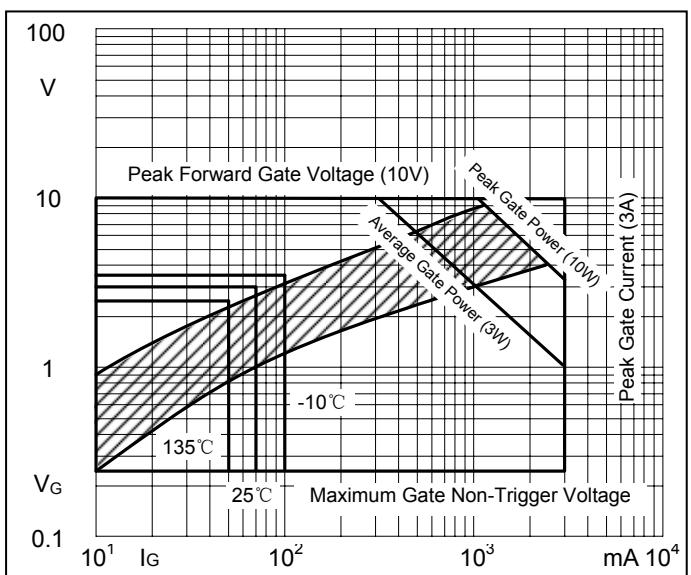
**Fig7. SCR Forward Current Derating Curve**



**Fig8. SCR Transient thermal impedance**



**Fig9. SCR Forward Characteristics**



**Fig10. Gate trigger Characteristics**

**Package Outline Information**

**CASE: M4**

